

Shenzhen Hualian Zhichuang Industrial Co., LTD



深圳市华联智创实业有限公司

产品规格书

SPECIFICATION

DESCRIPTION Chip Antenna

PART NO. SKT321606

VERSION V2.1

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1. Naming Rules

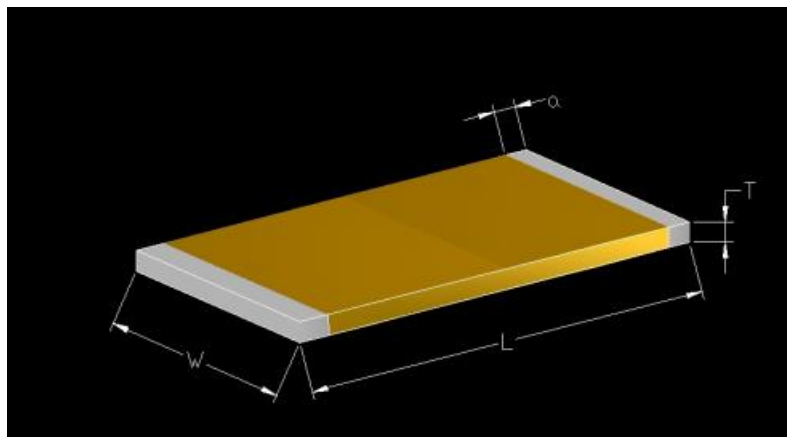
Type: SKT-ABCDEF-GH-IJ-K

1. SKT: Shortcut for Thinkte
2. ABCDEF: AB: Length(mm) CD: Width(mm)
For example: 502010 5.0mm*2.0mm
3. G: Material (C- Ceramic P-Polymer)
4. H: Feeding (S- Single D - Dual)
5. IJ: Version (01 - 99)
6. K: Package (R - Reel, T - Tape)

2. Antenna Specification

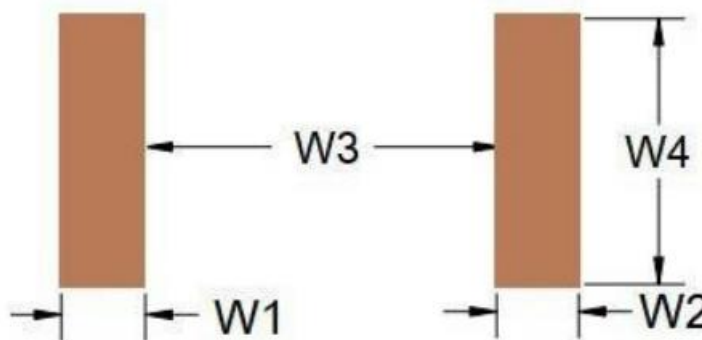
Outline Dimensions	3.2x1.6x0.6(mm)
Ground Plane	3.2x1.6(mm)
Frequency Range	2.4GHz ~ 2.5GHz
Impedance	50 Ohm Nominal
Bandwidth (under-10dBreturnloss)	100MHz (Typ.)
Radiation	Omni-directional
Peak Gain	1.3 dBi (Typ.)
Efficiency	60% (Typ.)
Polarization	Linear Polarization
Storage Temp	-40°C ~ +85°C
Color	Brown

3. Antenna Dimensi



Type	L	W	T	a
SKT3216	3.2 ±0.2	1.6 ±0.2	0.6 ±0.2	0.4 ±0.2

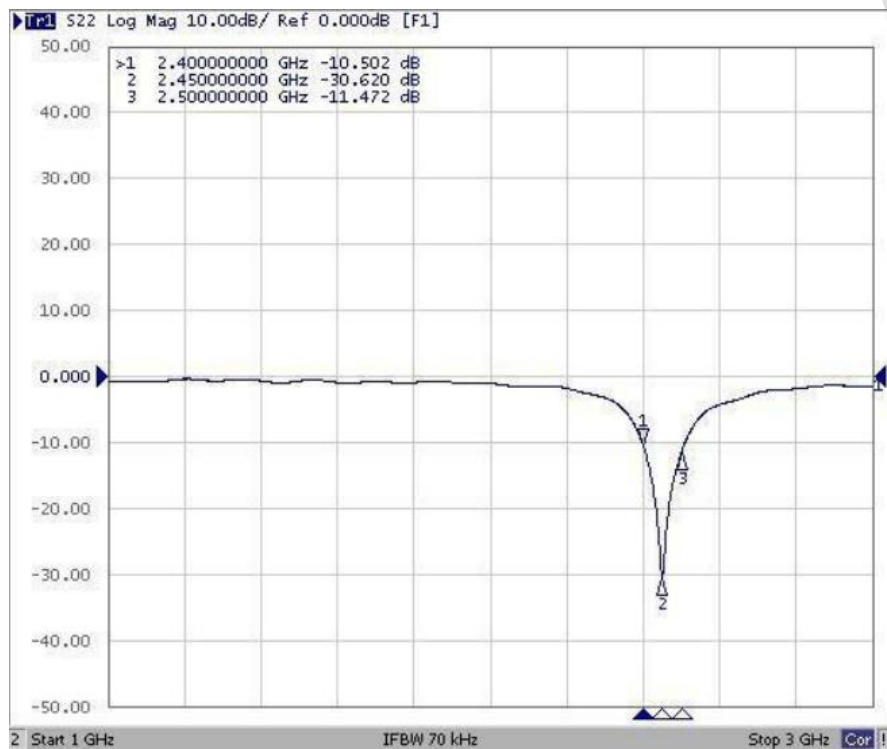
FootPrint (Unit : mm)



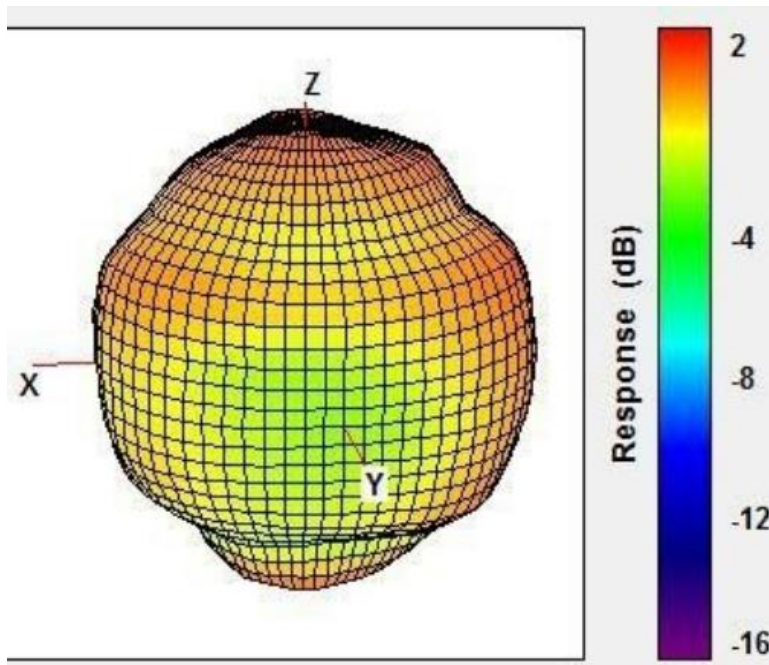
Type	W1	W2	W3	W4
SKT3216	0.4 ±0.2	0.4 ±0.2	2.4 ±0.2	1.6 ±0.2

4. Test Data:

4.1 ELECTRICAL CHARACTERISTICS

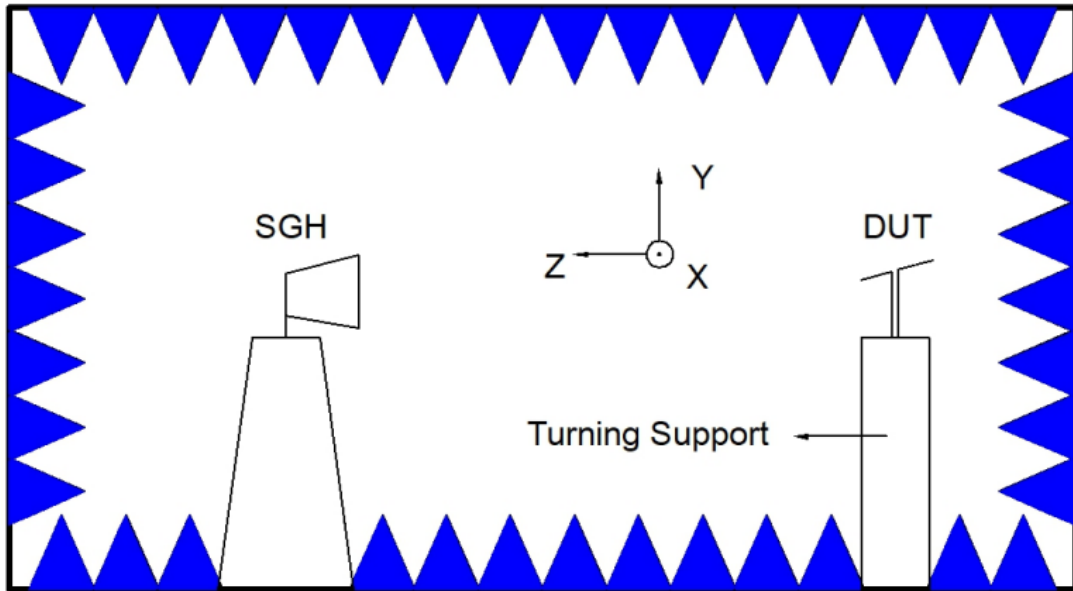


4.2 Radiation Pattern



	Efficiency	Peak
2400MHz	57.45%	1.3 dBi
2450MHz	60.65%	1.75dBi
2500MHz	56.75%	1.45dBi

Chamber Coordinate System

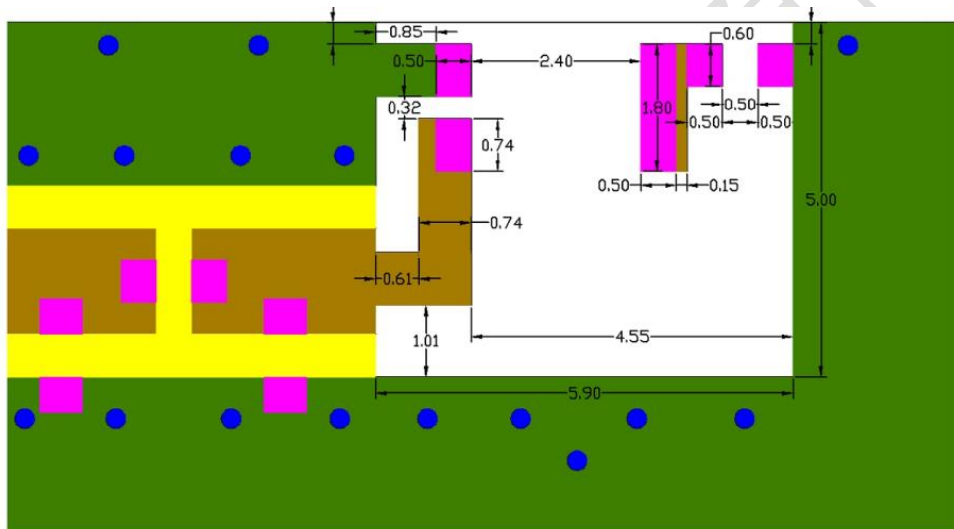


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5. LayoutGuide:

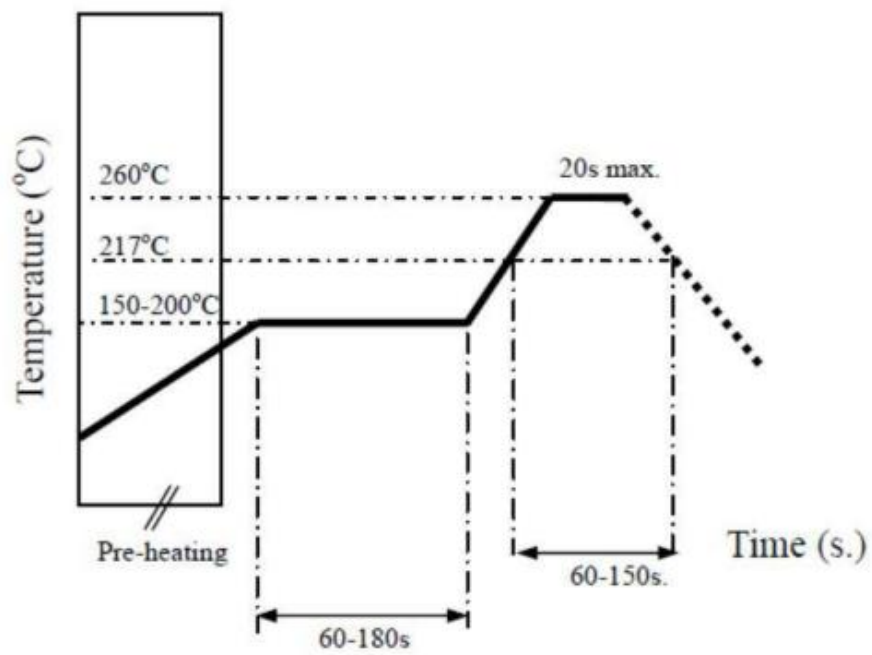
Solder Land Pattern:

Land pattern for soldering (black marking areas) is as shown below. Matching circuit is needed for good performance, when customer's device is different.



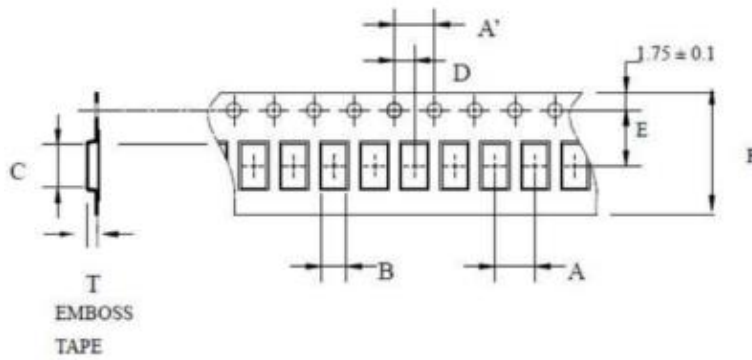
6. Soldering Conditions:

Typical Soldering Profile for Lead-free Process



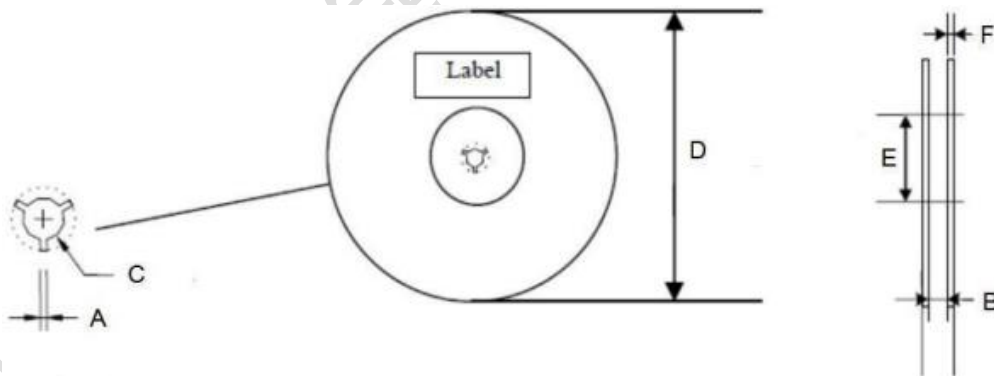
7. Taping Specifications:

Tape Dimensions (Unit: mm) & Quantity



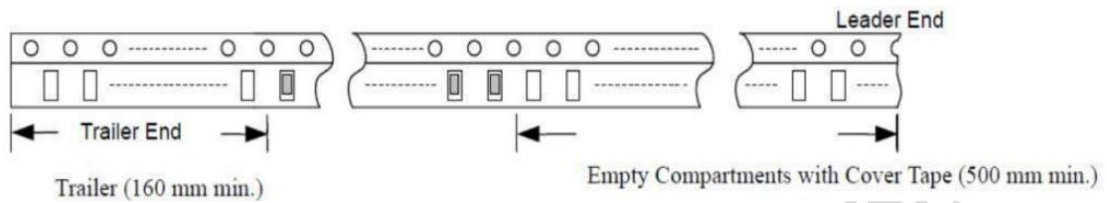
Type	A	A'	B	C	D	E	F	T	Quantity/Reel	Type Material
SKT2012	4.0 ±0.1	4.0 ±0.1	1.95 ±0.1	3.50 ±0.1	2.0 ±0.05	3.5 ±0.1	8.0 ±0.1	0.85 ±0.1	4,000pcs	Plastic (Embossed)

Reel Dimensions (Unit: mm)



Type	A	B	C	D	E	F
SKT2012	2.3 ±0.5	17 ±0.5	13.5 ±0.5	178 ±1	75 ±3	1.4 ±0.2

Leader and Trailer Tap



Soldering Conditions:

- (1) Temperature: 5~35°C, relative humidity (RH): 45~75%.
- (2) Non-corrosive environment